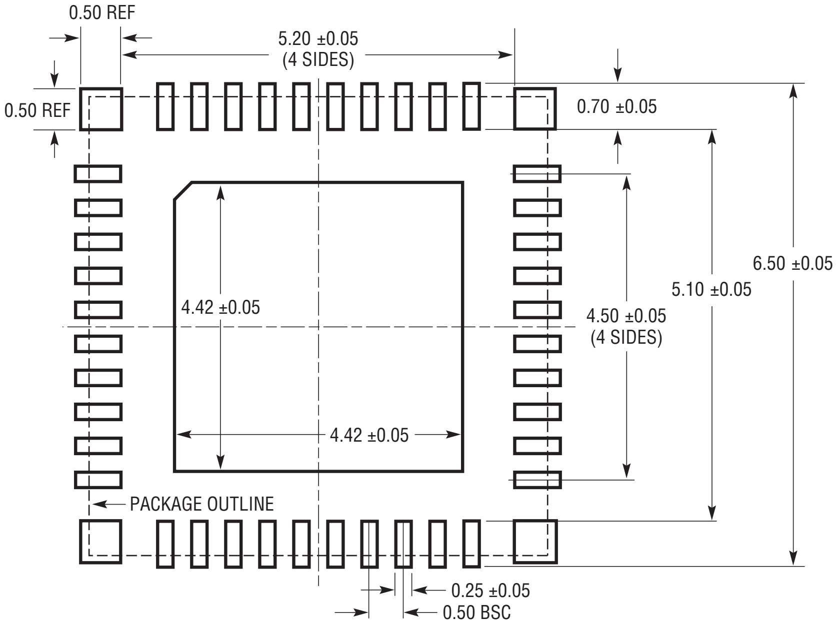
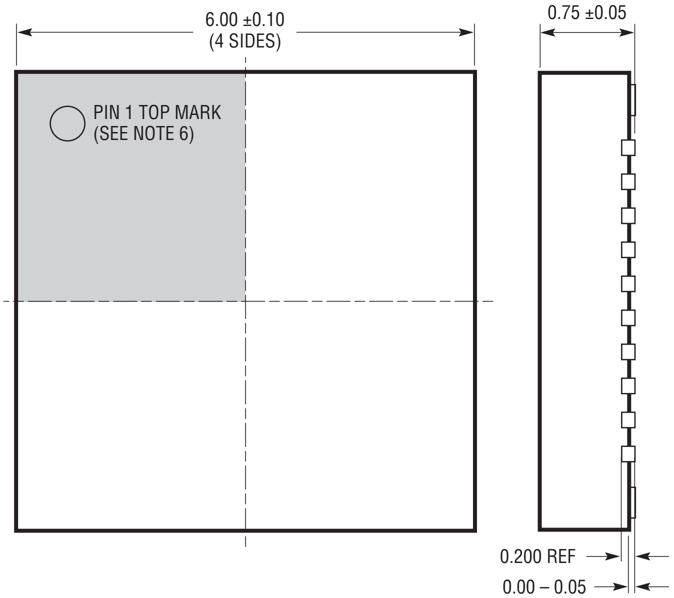
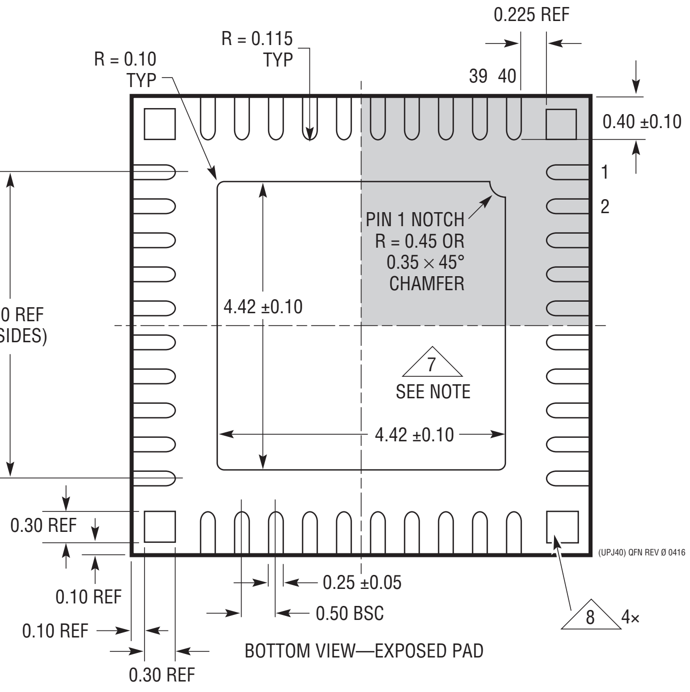
UPJ Package
40-Lead Plastic QFN (6mm × 6mm)

(Reference LTC DWG # 05-08-1545 Rev Ø)



RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED





NOTE:
1. DRAWING IS A JEDEC PACKAGE OUTLINE VARIATION REFER MO-220
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE
MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE, IF PRESENT
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
7. EXPOSED PAD
8. MECHANICAL REINFORCEMENT LAND PAD, ELECTRICALLY CONNECTED TO EXPOSED PAD